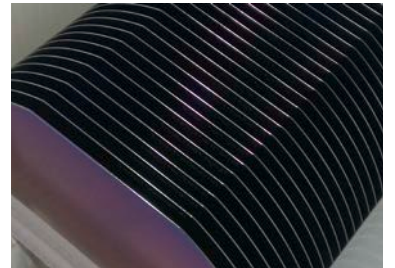
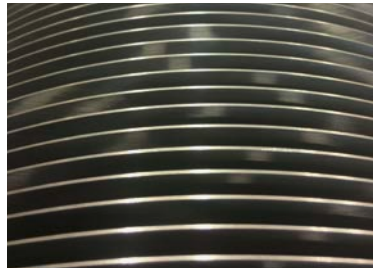
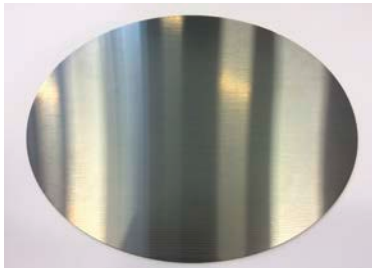


DW 292-300





MULTI WIRE SAW



WORK PIECE DIMENSIONS:
MAX. Ø 305 MM × 650 MM



12" WAFER AT HIGHEST PRECISION AND THROUGHPUT

-  Slurry and Diamond Wire compatible
-  High wire speed and acceleration
-  Minimized deflection roller amount
-  High process automation

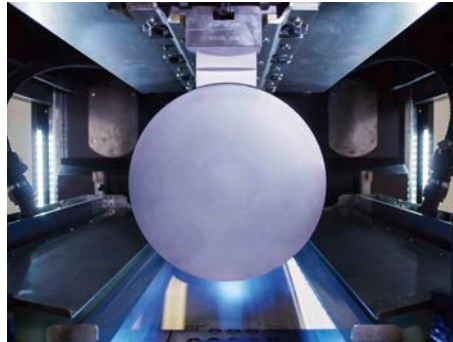
SMART SLICING TECHNOLOGY FOR SEMICONDUCTOR WAFERING

HIGHLIGHTS DW 292-300

- ✔ Slurry and Diamond Wire compatible
- ✔ Fast and easy change to Diamond Wire
- ✔ High throughput: 35 m/s wire speed, 12 m/s² acceleration
- ✔ 60 µm wire capability
- ✔ Perfect accessibility for daily operation
- ✔ Robust machine: Mineral cast, low temperature dependency, low vibration, low noise
- ✔ Shortest wire path: Only <1.9 m on one side, easy wire set-up and constant tension
- ✔ HMI: New HMI on 19" touch screen, production assistant, global process recipes, easy to train, easy to use
- ✔ Option: Automatic cutting fluid exchange
- ✔ Option: MES interface (SECS/GEM)



Long load length for high output



Optimized axis distance for higher wafer quality



Easy operation for higher yield

TECHNICAL DATA	DW 292-300 FEATURES
Web length [mm]	660
Max. work piece dimensions [mm]	Ø 305 × 650
Wire speed [m/sec]	Slurry: 20 / DW: 35
Wire acceleration [m/s ²]	Slurry: 8 (< 3s) / DW: 12 (< 3.5s)
Min. wire diameter [µm]	60
Max. wire tension [N]	34
Deflection Roller [pcs]	6
Wire guide roller [pcs]	3
Cutting fluid tank [l]	300
Machine dimensions [L × W × H] [mm]	3610 × 1380 × 2860
Machine weight [kg]	9300

GET IN TOUCH WITH US TODAY
TOGETHER WE WILL FIND A SOLUTION
FOR YOUR REQUIREMENTS

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